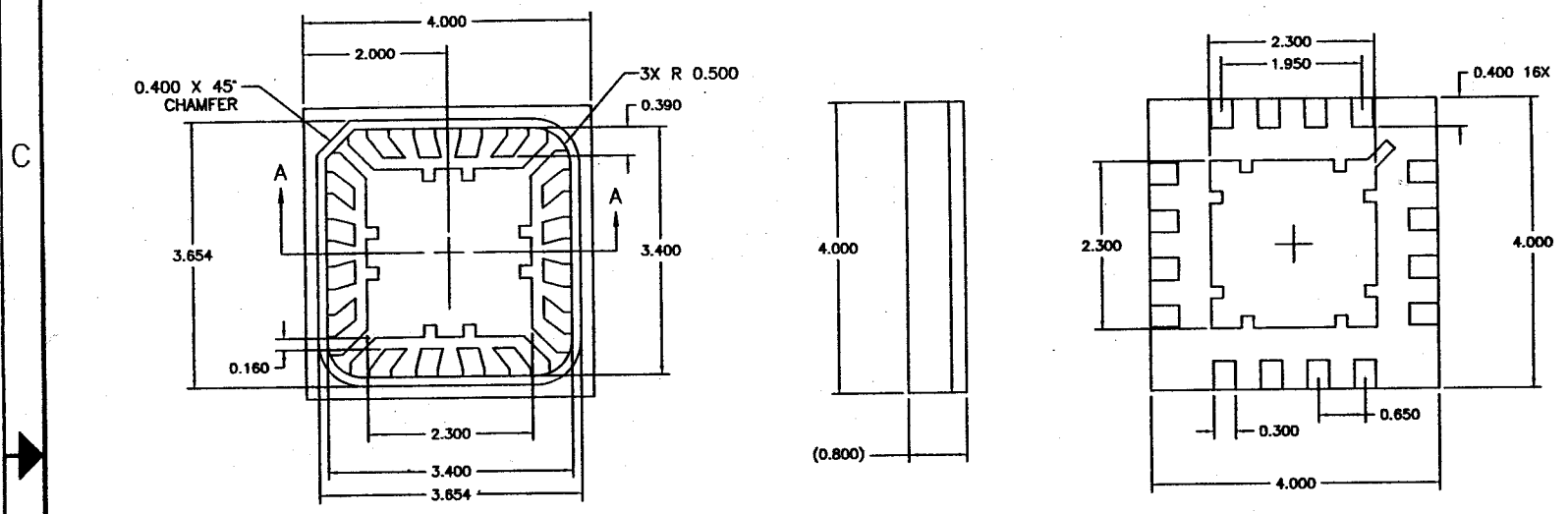


SSM P/N QFN01603

REVISIONS			
EDN NO.	DATE	DESCRIPTION	APPROVED
10473	10/17/05	PRODUCTION RELEASE	D.BENANDO



TOP VIEW

BOTTOM VIEW

SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. LEAD FINISH: FULL GOLD PLATE.
 5. FRAME THICKNESS: 0.2030 ± 0.0076.
 6. DIE PAD: 2.300mm X 2.300mm.
 7. JEDEC OUTLINE: MO-220 (VGGC-2)

<p>THIRD ANGLE PROJECTION</p> <p>UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS</p> <p>TOLERANCES ARE:</p> <p>X.XX ± 0.15 X.XXX ± 0.05</p> <p>X.XXX ± 0.050 ANGLES: ± 1°</p> <p>DO NOT SCALE DRAWING</p>	DRAWN BY	DATE
	APP BY	DATE
	CUSTOMER	

16 Lead 4.00mm x 4.00mm

QFN4X4-016-REV1

